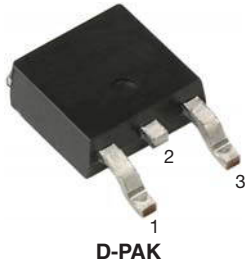
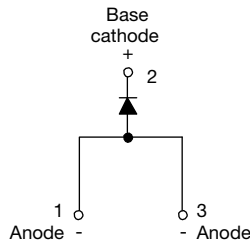


Surface Mount Fast Soft Recovery Rectifier Diode, 8 A



D-PAK



FEATURES

- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Material categorization:
For definitions of compliance please see www.vishay.com/doc?99912



RoHS
COMPLIANT

APPLICATIONS

- Output rectification and freewheeling diode in inverters, choppers and converters
- Input rectifications where severe restrictions on conducted EMI should be met

DESCRIPTION

The VS-8EWF..S-M3 fast soft recovery rectifier series has been optimized for combined short reverse recovery time, low forward voltage drop and low leakage current.

The glass passivation ensures stable reliable operation in the most severe temperature and power cycling conditions.

PRODUCT SUMMARY	
Package	D-PAK (TO-252AA)
$I_{F(AV)}$	8 A
V_R	1000 V, 1200 V
V_F at I_F	1.3 V
I_{FSM}	150 A
t_{rr}	80 ns
T_J max.	150 °C
Diode variation	Single die
Snap factor	0.6

MAJOR RATINGS AND CHARACTERISTICS			
SYMBOL	CHARACTERISTICS	VALUES	UNITS
$I_{F(AV)}$	Sinusoidal waveform	8	A
V_{RRM}		1000/1200	V
I_{FSM}		150	A
V_F	8 A, $T_J = 25$ °C	1.3	V
t_{rr}	1 A, 100 A/ μ s	80	ns
T_J	Range	-40 to 150	°C

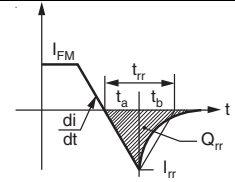
VOLTAGE RATINGS			
PART NUMBER	V_{RRM} , MAXIMUM PEAK REVERSE VOLTAGE V	V_{RSM} , MAXIMUM NON-REPETITIVE PEAK REVERSE VOLTAGE V	I_{RRM} AT 150 °C mA
8EWF10SPbF	1000	1100	4
8EWF12SPbF	1200	1300	

ABSOLUTE MAXIMUM RATINGS				
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum average forward current	$I_{F(AV)}$	$T_C = 94$ °C, 180° conduction half sine wave	8	A
Maximum peak one cycle non-repetitive surge current	I_{FSM}	10 ms sine pulse, rated V_{RRM} applied	125	
		10 ms sine pulse, no voltage reapplied	150	
Maximum I^2t for fusing	I^2t	10 ms sine pulse, rated V_{RRM} applied	78	A^2s
		10 ms sine pulse, no voltage reapplied	110	
Maximum $I^2\sqrt{t}$ for fusing	$I^2\sqrt{t}$	$t = 0.1$ to 10 ms, no voltage reapplied	1100	$A^2\sqrt{s}$



ELECTRICAL SPECIFICATIONS					
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum forward voltage drop	V_{FM}	8 A, $T_J = 25\text{ }^\circ\text{C}$		1.3	V
Forward slope resistance	r_t	$T_J = 150\text{ }^\circ\text{C}$		25.6	$\text{m}\Omega$
Threshold voltage	$V_{F(TO)}$			0.93	V
Maximum reverse leakage current	I_{RM}	$T_J = 25\text{ }^\circ\text{C}$	$V_R = \text{Rated } V_{RRM}$	0.1	mA
		$T_J = 150\text{ }^\circ\text{C}$		4	

RECOVERY CHARACTERISTICS				
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Reverse recovery time	t_{rr}	I_F at 8 A _{pK} 25 A/ μs $T_J = 25\text{ }^\circ\text{C}$	270	ns
Reverse recovery current	I_{rr}		4.2	A
Reverse recovery charge	Q_{rr}		1	μC
Snap factor	S		0.6	



THERMAL - MECHANICAL SPECIFICATIONS				
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum junction and storage temperature range	T_J, T_{Stg}		-40 to 150	$^\circ\text{C}$
Maximum thermal resistance, junction to case	R_{thJC}	DC operation	2.5	$^\circ\text{C/W}$
Typical thermal resistance, junction to ambient (PCB mount)	$R_{thJA}^{(1)}$		50	
Soldering temperature	T_S	For 10 seconds	260	$^\circ\text{C}$
Approximate weight			1	g
			0.03	oz.
Marking device		Case style D-PAK (TO-252AA)	8EWF12S	

Note

⁽¹⁾ When mounted on 1" square (650 mm²) PCB of FR-4 or G-10 material 4 oz. (140 μm) copper 40 $^\circ\text{C/W}$
For recommended footprint and soldering techniques refer to application note #AN-994

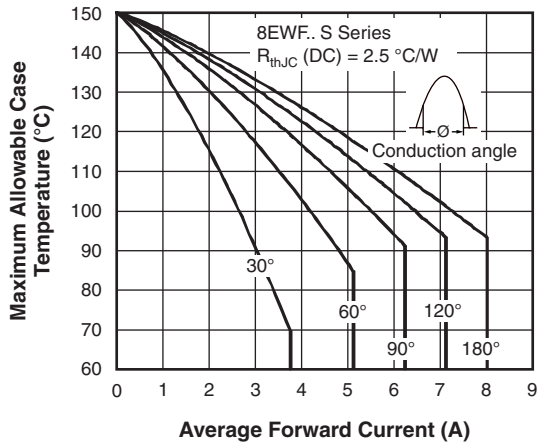


Fig. 1 - Current Rating Characteristics

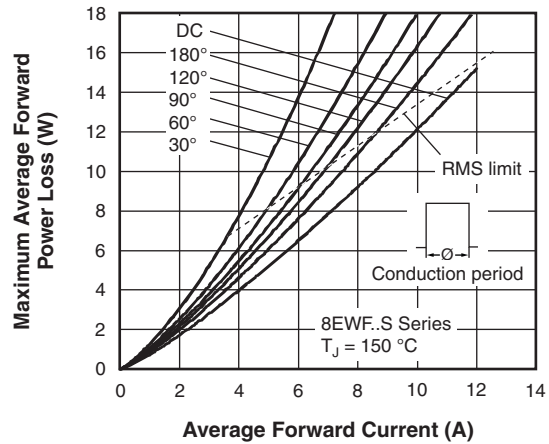


Fig. 4 - Forward Power Loss Characteristics

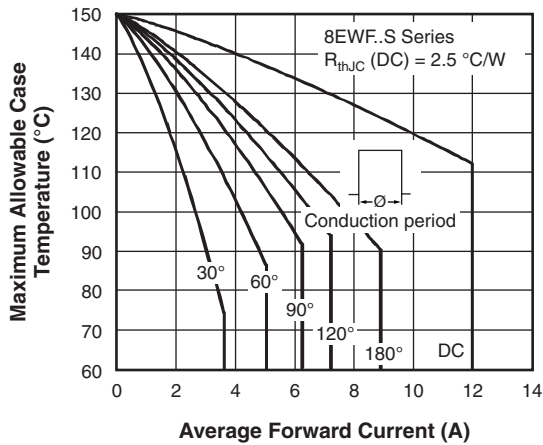


Fig. 2 - Current Rating Characteristics

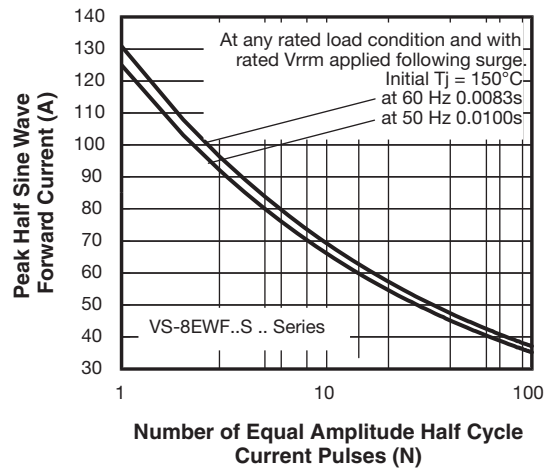


Fig. 5 - Maximum Non-Repetitive Surge Current

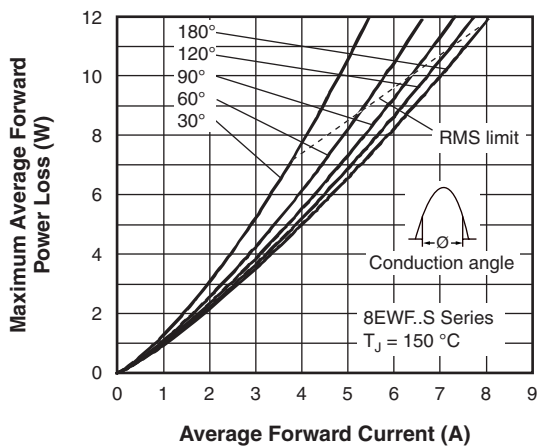


Fig. 3 - Forward Power Loss Characteristics

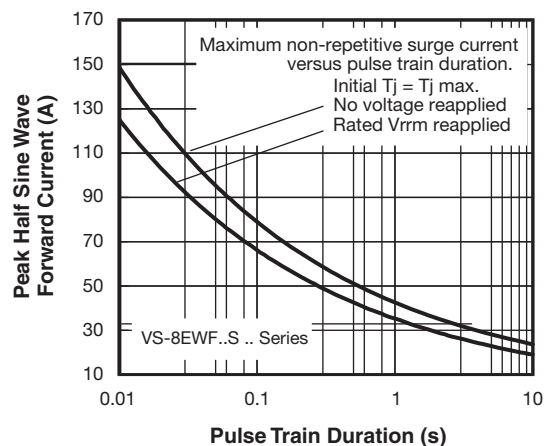


Fig. 6 - Maximum Non-Repetitive Surge Current

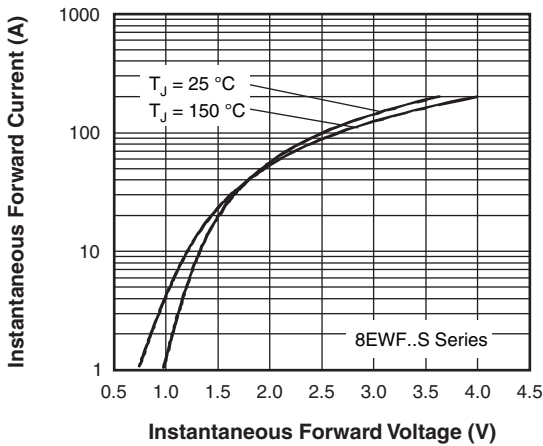


Fig. 7 - Forward Voltage Drop Characteristics

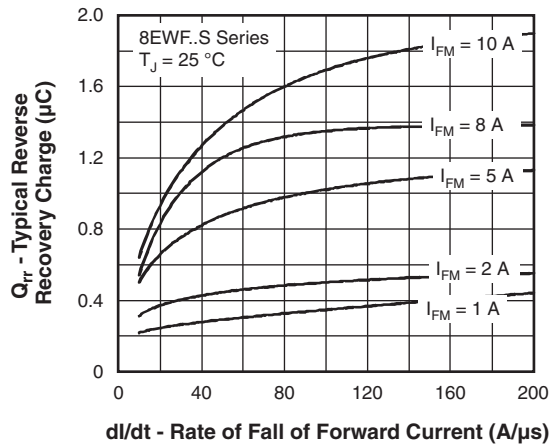


Fig. 10 - Recovery Charge Characteristics, $T_J = 25\text{ }^\circ\text{C}$

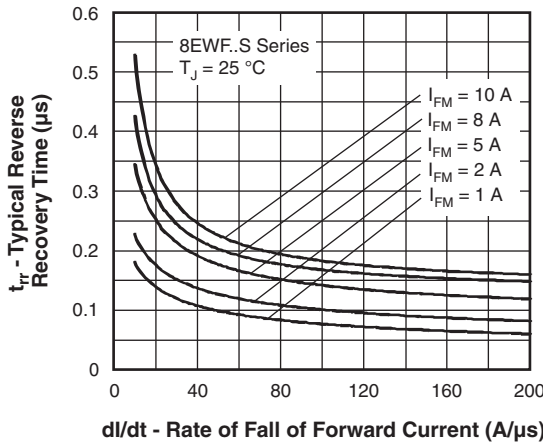


Fig. 8 - Recovery Time Characteristics, $T_J = 25\text{ }^\circ\text{C}$

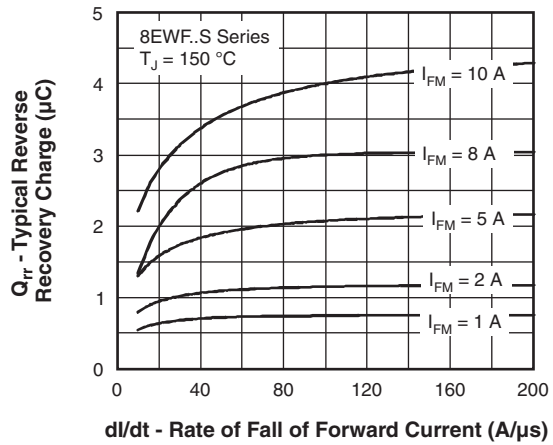


Fig. 11 - Recovery Charge Characteristics, $T_J = 150\text{ }^\circ\text{C}$

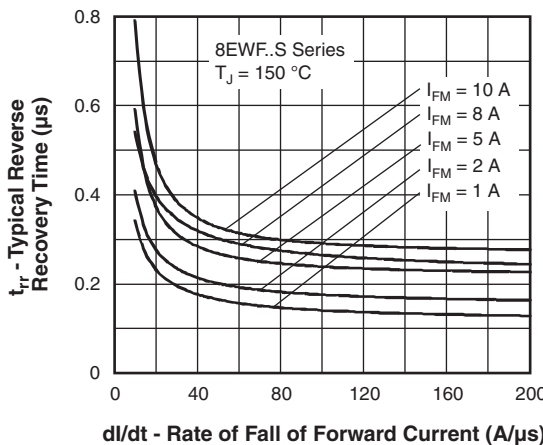


Fig. 9 - Recovery Time Characteristics, $T_J = 150\text{ }^\circ\text{C}$

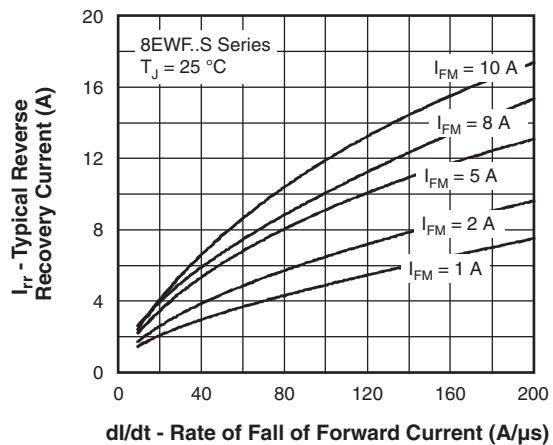


Fig. 12 - Recovery Current Characteristics, $T_J = 25\text{ }^\circ\text{C}$

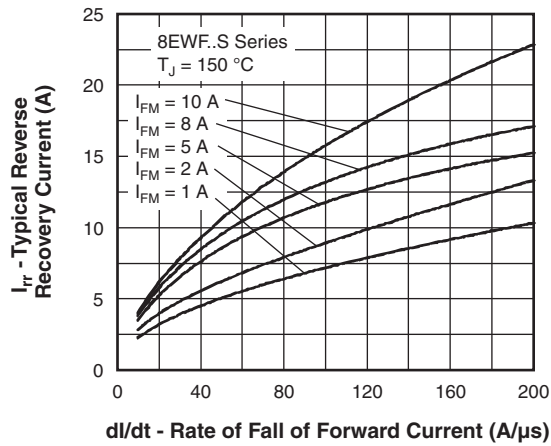


Fig. 13 - Recovery Current Characteristics, $T_J = 150\text{ }^\circ\text{C}$

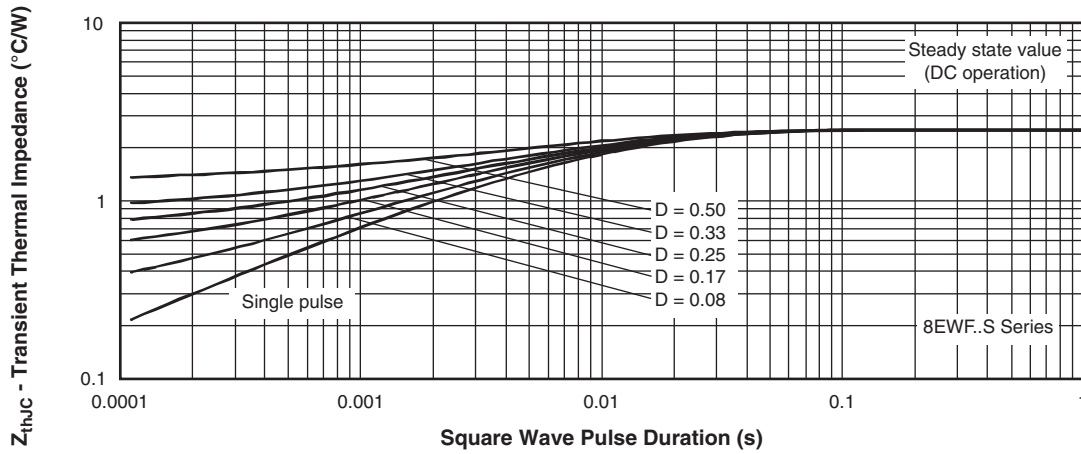
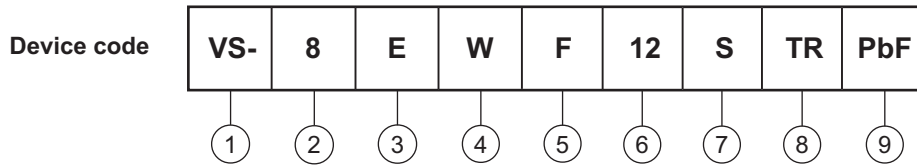


Fig. 14 - Thermal Impedance Z_{thJC} Characteristics



ORDERING INFORMATION TABLE



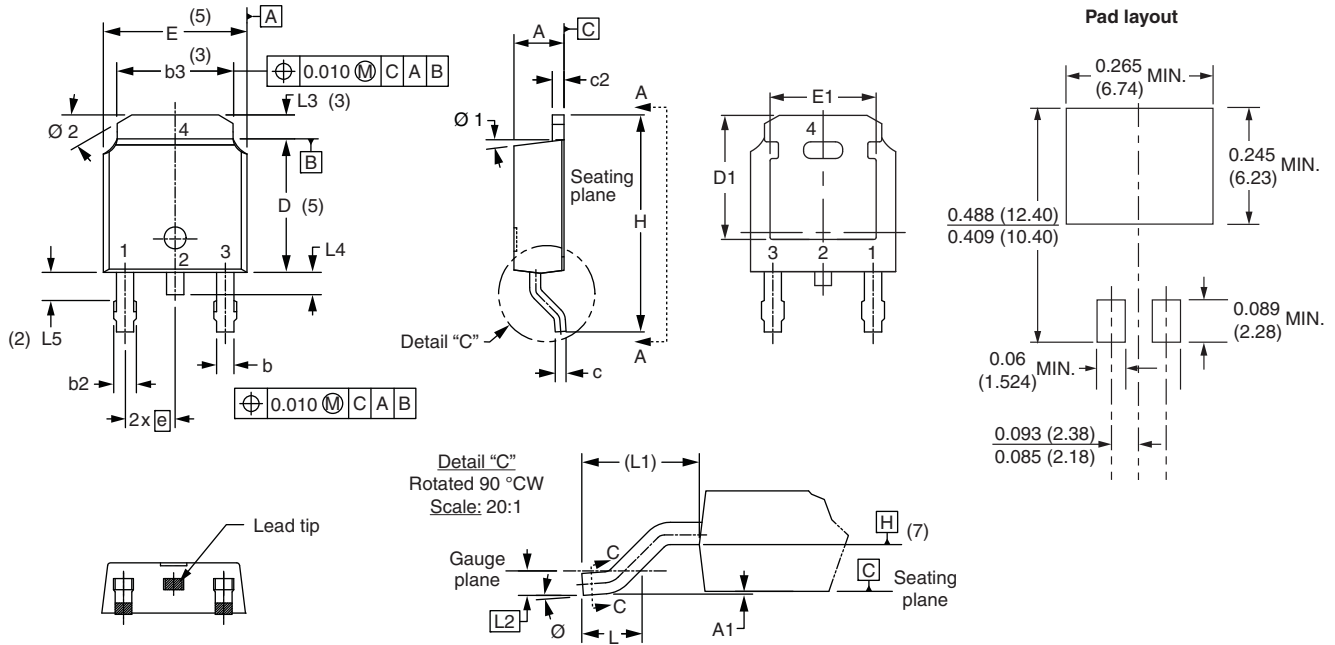
- 1** - Vishay Semiconductors product
- 2** - Current rating (8 = 8 A)
- 3** - Circuit configuration:
E = Single diode
- 4** - Package:
W = D-PAK
- 5** - Type of silicon:
F = Fast soft recovery rectifier
- 6** - Voltage code x 100 = V_{RRM}

10 = 1000 V
12 = 1200 V
- 7** - S = Surface mountable
- 8** -
 - TR = Tape and reel
 - TRR = Tape and reel (right oriented)
 - TRL = Tape and reel (left oriented)
- 9** -
 - None = Standard production
 - PbF = Lead (Pb)-free

LINKS TO RELATED DOCUMENTS	
Dimensions	www.vishay.com/doc?95016
Part marking information	www.vishay.com/doc?95059
Packaging information	www.vishay.com/doc?95033
SPIICE model	www.vishay.com/doc?95552

D-PAK (TO-252AA)

DIMENSIONS in millimeters and inches



SYMBOL	MILLIMETERS		INCHES		NOTES	SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.			MIN.	MAX.	MIN.	MAX.	
A	2.18	2.39	0.086	0.094		e	2.29 BSC		0.090 BSC		
A1	-	0.13	-	0.005		H	9.40	10.41	0.370	0.410	
b	0.64	0.89	0.025	0.035		L	1.40	1.78	0.055	0.070	
b2	0.76	1.14	0.030	0.045		L1	2.74 BSC		0.108 REF.		
b3	4.95	5.46	0.195	0.215	3	L2	0.51 BSC		0.020 BSC		
c	0.46	0.61	0.018	0.024		L3	0.89	1.27	0.035	0.050	3
c2	0.46	0.89	0.018	0.035		L4	-	1.02	-	0.040	
D	5.97	6.22	0.235	0.245	5	L5	1.14	1.52	0.045	0.060	2
D1	5.21	-	0.205	-	3	Ø	0°	10°	0°	10°	
E	6.35	6.73	0.250	0.265	5	Ø1	0°	15°	0°	15°	
E1	4.32	-	0.170	-	3	Ø2	25°	35°	25°	35°	

Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Lead dimension uncontrolled in L5
- (3) Dimension D1, E1, L3 and b3 establish a minimum mounting surface for thermal pad
- (4) Section C - C dimension apply to the flat section of the lead between 0.13 and 0.25 mm (0.005 and 0.10") from the lead tip
- (5) Dimension D, and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (6) Dimension b1 and c1 applied to base metal only
- (7) Datum A and B to be determined at datum plane H
- (8) Outline conforms to JEDEC outline TO-252AA



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